



FOR IMMEDIATE RELEASE

November 30, 2005 09:00 AM US Eastern Timezone

ISSYS Receives Phase I SBIR Grant from NSF for Development of Wafer-Scale, Hermetic Packaging of Intelligent MEMS-Based Systems

YPSILANTI, Mich.--(BUSINESS WIRE)--Nov. 30, 2005--Integrated Sensing Systems, Inc. (ISSYS) announced today that it has won a Small Business Innovation Research contract from the National Science Foundation (NSF). The six-month project, entitled "Wafer-Scale, Hermetic, Packaging of MEMS-Based Systems" is aimed towards development of a novel packaging method which will greatly simplify the packaging of MEMS and their associated electronics. This simplification allows the commercialization of a variety of MEMS-based products that are currently not possible due to high cost of manufacturing or packaging problems. ISSYS' method can be used for a wide variety of MEMS based devices, in particular, for applications where the MEMS device needs to be in direct contact with the media and the electronics need to be isolated from the environment.

Ms. Sonbol Massoud-Ansari, project's Principal Investigator and Vice President of ISSYS, stated that, "Our packaging method will allow a low-cost, robust, and manufacturable solution for hermetic hybrid integration of MEMS and electronics which is one of the most challenging and important problems in commercialization of MEMS devices. We greatly appreciate the support from NSF, which will allow us to expedite the development of this novel packaging solution."

ISSYS Background: ISSYS is a leader in advanced micromachining technologies for medical devices, microfluidic and scientific analytical sensing applications used in the development of drug infusion pumps and wireless, implantable sensing systems. Founded in 1995 by world-renowned leaders in MEMS technology, ISSYS is one of the oldest independent MEMS companies in the United States. An ISO 9001:2000 certified organization, ISSYS operates an "everything under one roof" multi-million-dollar, state-of-the-art Bio-MEMS fabrication facility located near Ann Arbor, Michigan. For more company, product and service information, please visit <http://www.mems-issys.com/>.

Contacts:

Integrated Sensing Systems, Inc.
Sonbol Massoud-Ansari, 734-547-9896 Ext. 104
Fax: 734-547-9964
Email: sonbol@mems-issys.com